

Serial No. 10/026,811

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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-15 (canceled)

Claim 16 (currently amended): A method of manufacturing an electronic element, comprising the steps of:

providing a piezoelectric substrate;

forming electrode pads on the piezoelectric substrate;

disposing base electrodes on the electrode pads;

~~disposing intermediate electrodes on the electrode pads~~the base electrodes, said intermediate electrodes including such that the base electrodes are located between said electrode pads and said intermediate electrodes;

forming bump electrodes on the intermediate electrodes;

disposing the electronic element on a package having package electrodes such that said bump electrodes opposes said package electrodes; and

press-bonding said package electrodes to said bump electrodes while applying ultrasonic waves or heat;

wherein said intermediate electrodes are ~~is~~ made of at least one of Al and an alloy including Al; and

said base electrodes include a metallic material that increases the half-width of a locking curve of an X-ray diffraction peak from a (111) plane of Al in said intermediate electrodes to greater than about 15 degrees.

Claim 17 (original): The method of claim 16, further comprising sealing the package airtight with a cap.

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Claim 18 (currently amended): The method of claim 16, further comprising providing additional intermediate electrodes having a plurality of layers, and disposing ~~said-additional~~ base electrodes between said layers of said intermediate electrodes.

Claim 19 (original): The method of claim 16, wherein said bump electrodes are made of a metal having a melting point of about 450°C or more.

Claim 20 (canceled)